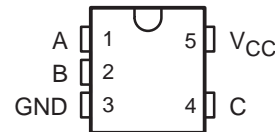


# SN74LVC1G66 SINGLE BILATERAL ANALOG SWITCH

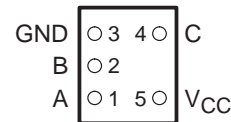
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- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- 1.65-V to 5.5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 0.8 ns at 3.3 V
- High On-Off Output Voltage Ratio
- High Degree of Linearity
- High Speed, Typically 0.5 ns ( $V_{CC} = 3$  V,  $C_L = 50$  pF)
- Low On-State Resistance, Typically  $\approx 5.5 \Omega$  ( $V_{CC} = 4.5$  V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE  
(TOP VIEW)



YEA, YEP, YZA, OR YZP PACKAGE  
(BOTTOM VIEW)



## description/ordering information

This single analog switch is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1G66 can handle both analog and digital signals. The device permits signals with amplitudes of up to 5.5 V (peak) to be transmitted in either direction.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
–40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA	Reel of 3000	SN74LVC1G66YEAR	---C6_
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)		SN74LVC1G66YZAR	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC1G66YEPR	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC1G66YZPR	
–40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G66DBVR	C66_
		Reel of 250	SN74LVC1G66DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G66DCKR	C6_
		Reel of 250	SN74LVC1G66DCKT	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

‡ DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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# SN74LVC1G66

## SINGLE BILATERAL ANALOG SWITCH

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### description/ordering information (continued)

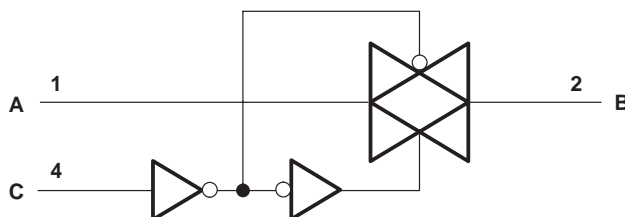
NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

FUNCTION TABLE

CONTROL INPUT (C)	SWITCH
L	OFF
H	ON

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ (see Note 1)	-0.5 V to 6.5 V
Input voltage range, $V_I$ (see Notes 1 and 2)	-0.5 V to 6.5 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1, 2, and 3)	-0.5 V to $V_{CC} + 0.5$ V
Control input clamp current, $I_{IK}$ ( $V_I < 0$ )	-50 mA
I/O port diode current, $I_{IOK}$ ( $V_{I/O} < 0$ or $V_{I/O} > V_{CC}$ )	±50 mA
On-state switch current, $I_T$ ( $V_{I/O} = 0$ to $V_{CC}$ )	±50 mA
Continuous current through $V_{CC}$ or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 4):	
DBV package	206°C/W
DCK package	252°C/W
YEA/YZA package	154°C/W
YEP/YZP package	132°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltages are with respect to ground, unless otherwise specified.
  2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  3. This value is limited to 5.5 V maximum.
  4. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVC1G66 SINGLE BILATERAL ANALOG SWITCH

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## recommended operating conditions (see Note 5)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	1.65	5.5	V
V <sub>I/O</sub>	I/O port voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage, control input	V <sub>CC</sub> = 1.65 V to 1.95 V	V <sub>CC</sub> × 0.65	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7	
V <sub>IL</sub>	Low-level input voltage, control input	V <sub>CC</sub> = 1.65 V to 1.95 V	V <sub>CC</sub> × 0.35	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.3	
V <sub>I</sub>	Control input voltage	0	5.5	V
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 1.65 V to 1.95 V	20	ns/V
		V <sub>CC</sub> = 2.3 V to 2.7 V	20	
		V <sub>CC</sub> = 3 V to 3.6 V	10	
		V <sub>CC</sub> = 4.5 V to 5.5 V	10	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT
r <sub>on</sub>	On-state switch resistance V <sub>I</sub> = V <sub>CC</sub> or GND, V <sub>C</sub> = V <sub>IH</sub> (see Figures 1 and 2)	I <sub>S</sub> = 4 mA	1.65 V	12	30	Ω
		I <sub>S</sub> = 8 mA	2.3 V	9	20	
		I <sub>S</sub> = 24 mA	3 V	7.5	15	
		I <sub>S</sub> = 32 mA	4.5 V	5.5	10	
r <sub>on(p)</sub>	Peak on resistance V <sub>I</sub> = V <sub>CC</sub> to GND, V <sub>C</sub> = V <sub>IH</sub> (see Figures 1 and 2)	I <sub>S</sub> = 4 mA	1.65 V	74.5	100	Ω
		I <sub>S</sub> = 8 mA	2.3 V	20	30	
		I <sub>S</sub> = 24 mA	3 V	11.5	20	
		I <sub>S</sub> = 32 mA	4.5 V	7.5	15	
I <sub>S(off)</sub>	Off-state switch leakage current V <sub>I</sub> = V <sub>CC</sub> and V <sub>O</sub> = GND or V <sub>I</sub> = GND and V <sub>O</sub> = V <sub>CC</sub> ; V <sub>C</sub> = V <sub>IL</sub> (see Figure 3)	5.5 V		±1	±0.1†	μA
I <sub>S(on)</sub>	On-state switch leakage current V <sub>I</sub> = V <sub>CC</sub> or GND, V <sub>C</sub> = V <sub>IH</sub> , V <sub>O</sub> = Open (see Figure 4)	5.5 V		±1	±0.1†	μA
I <sub>I</sub>	Control input current V <sub>C</sub> = V <sub>CC</sub> or GND	5.5 V		±1	±0.1†	μA
I <sub>CC</sub>	Supply current V <sub>C</sub> = V <sub>CC</sub> or GND	5.5 V		10	1†	μA
ΔI <sub>CC</sub>	Supply current change V <sub>C</sub> = V <sub>CC</sub> - 0.6 V	5.5 V			500	μA
C <sub>ic</sub>	Control input capacitance	5 V		2		pF
C <sub>io(off)</sub>	Switch input/output capacitance	5 V		6		pF
C <sub>io(on)</sub>	Switch input/output capacitance	5 V		13		pF

† T<sub>A</sub> = 25°C



# SN74LVC1G66

## SINGLE BILATERAL ANALOG SWITCH

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub> <sup>†</sup>	A or B	B or A	2		1.2		0.8		0.6		ns
t <sub>en</sub> <sup>‡</sup>	C	A or B	2.5	12	1.9	6.5	1.8	5	1.5	4.2	ns
t <sub>dis</sub> <sup>§</sup>	C	A or B	2.2	10	1.4	6.9	2	6.5	1.4	5	ns

<sup>†</sup> t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>. The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

<sup>‡</sup> t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.

<sup>§</sup> t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.

### analog switch characteristics, T<sub>A</sub> = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
Frequency response <sup>¶</sup> (switch ON)	A or B	B or A	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 600 Ω, f <sub>in</sub> = sine wave (see Figure 6)	1.65 V	35	MHz
				2.3 V	120	
				3 V	175	
				4.5 V	195	
			C <sub>L</sub> = 5 pF, R <sub>L</sub> = 50 Ω, f <sub>in</sub> = sine wave (see Figure 6)	1.65 V	>300	
				2.3 V	>300	
				3 V	>300	
				4.5 V	>300	
Crosstalk (control input to signal output)	C	A or B	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 600 Ω, f <sub>in</sub> = 1 MHz (square wave) (see Figure 7)	1.65 V	35	mV
				2.3 V	50	
				3 V	70	
				4.5 V	100	
Feed-through attenuation <sup>#</sup> (switch OFF)	A or B	B or A	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 600 Ω, f <sub>in</sub> = 1 MHz (sine wave) (see Figure 8)	1.65 V	-58	dB
				2.3 V	-58	
				3 V	-58	
				4.5 V	-58	
			C <sub>L</sub> = 5 pF, R <sub>L</sub> = 50 Ω, f <sub>in</sub> = 1 MHz (sine wave) (see Figure 8)	1.65 V	-42	
				2.3 V	-42	
				3 V	-42	
				4.5 V	-42	
Sine-wave distortion	A or B	B or A	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 10 kΩ, f <sub>in</sub> = 1 kHz (sine wave) (see Figure 9)	1.65 V	0.1	%
				2.3 V	0.025	
				3 V	0.015	
				4.5 V	0.01	
			C <sub>L</sub> = 50 pF, R <sub>L</sub> = 10 kΩ, f <sub>in</sub> = 10 kHz (sine wave) (see Figure 9)	1.65 V	0.15	
				2.3 V	0.025	
				3 V	0.015	
				4.5 V	0.01	

<sup>¶</sup> Adjust f<sub>in</sub> voltage to obtain 0 dBm at output. Increase f<sub>in</sub> frequency until dB meter reads -3 dB.

<sup>#</sup> Adjust f<sub>in</sub> voltage to obtain 0 dBm at input.



# SN74LVC1G66 SINGLE BILATERAL ANALOG SWITCH

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operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	$V_{CC} = 5\text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
$C_{pd}$ Power dissipation capacitance	$f = 10\text{ MHz}$	8	9	9	11	pF

# SN74LVC1G66 SINGLE BILATERAL ANALOG SWITCH

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## PARAMETER MEASUREMENT INFORMATION

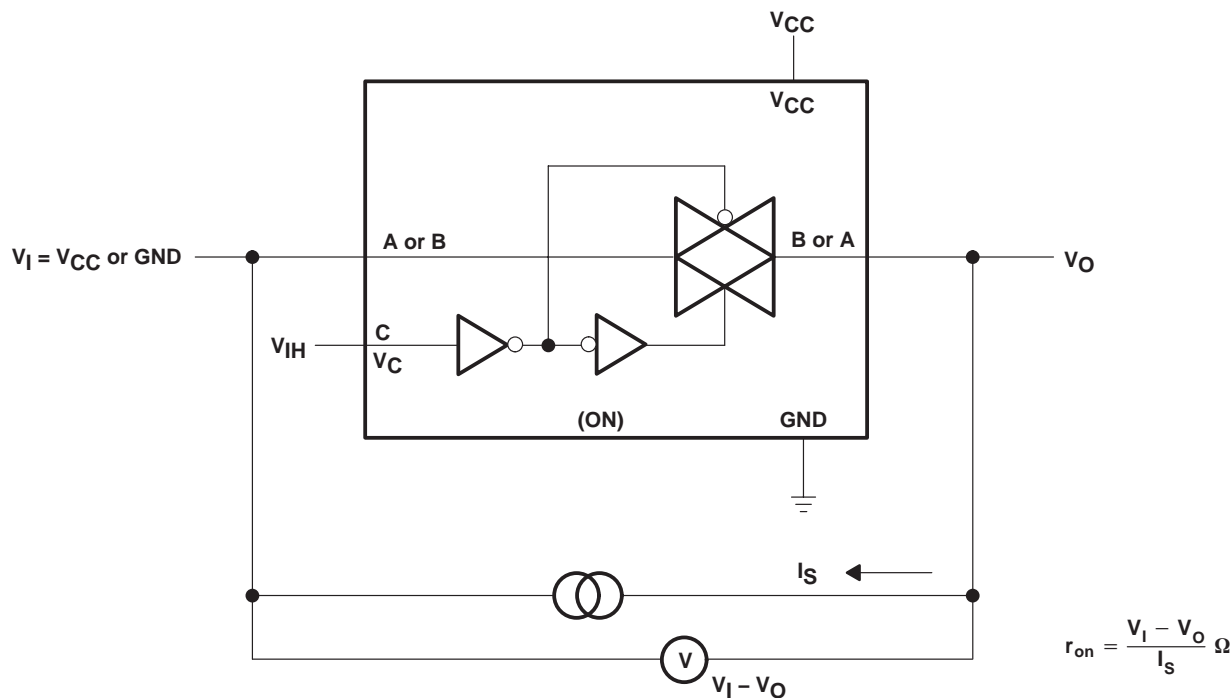


Figure 1. On-State Resistance Test Circuit

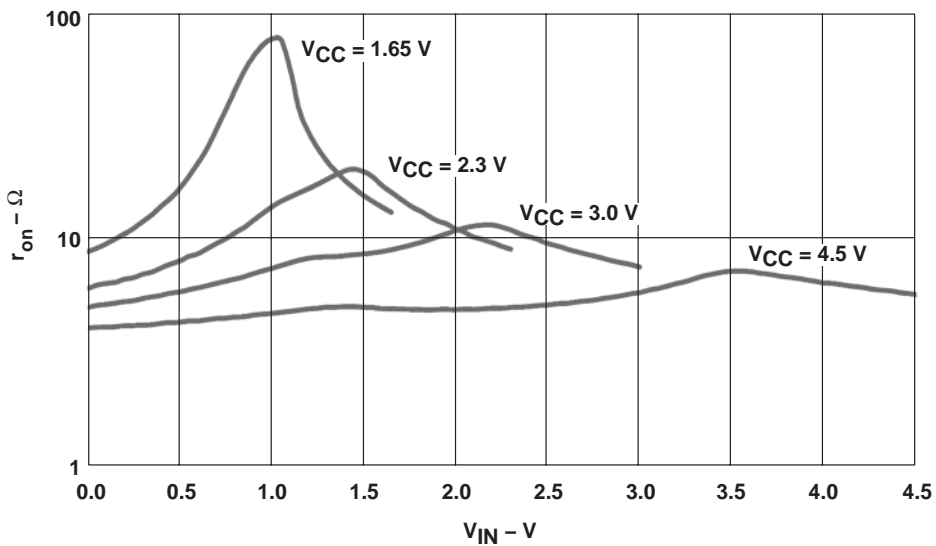


Figure 2. Typical  $r_{on}$  as a Function of Input Voltage ( $V_I$ ) for  $V_I = 0$  to  $V_{CC}$

PARAMETER MEASUREMENT INFORMATION

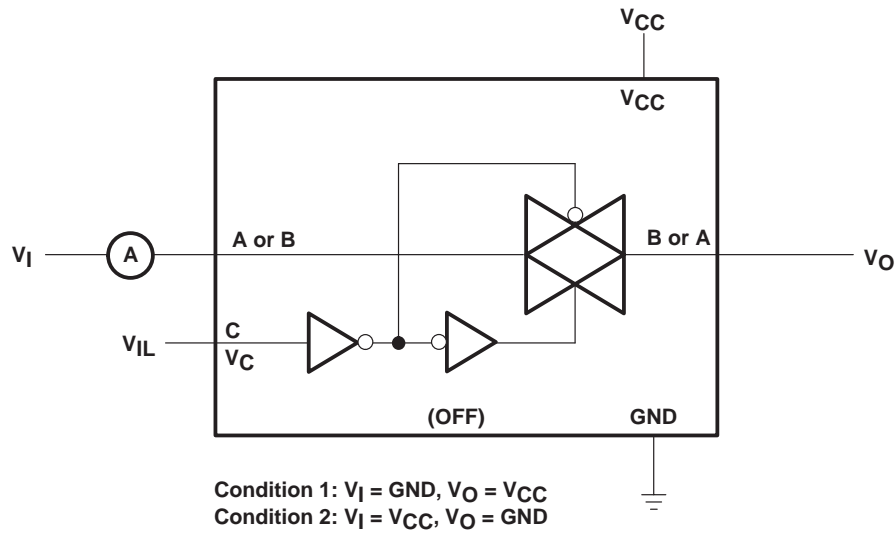


Figure 3. Off-State Switch Leakage-Current Test Circuit

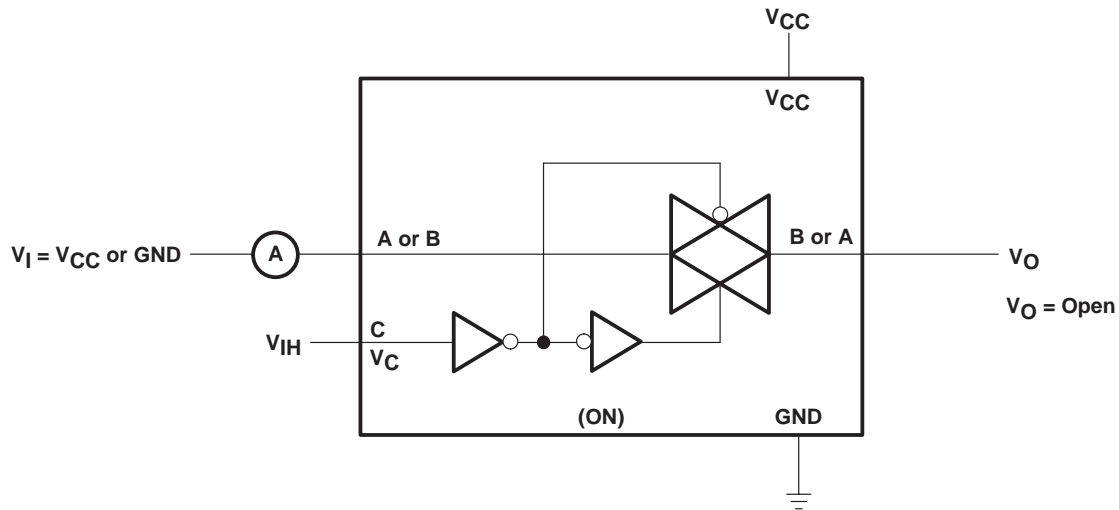
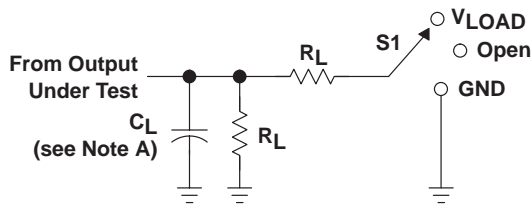


Figure 4. On-State Leakage-Current Test Circuit

# SN74LVC1G66 SINGLE BILATERAL ANALOG SWITCH

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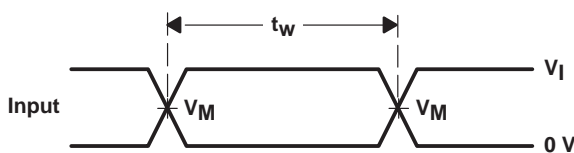
## PARAMETER MEASUREMENT INFORMATION



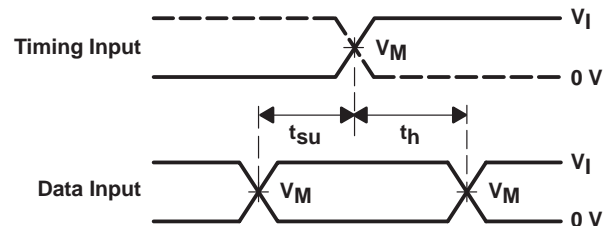
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

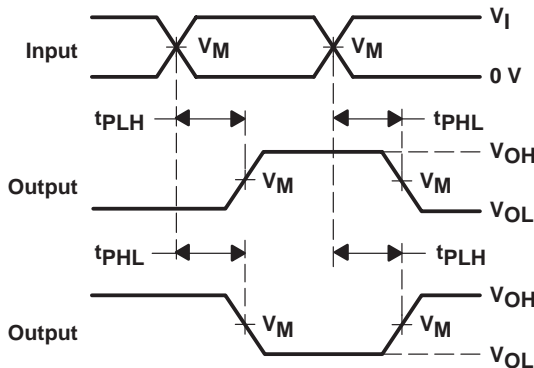
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



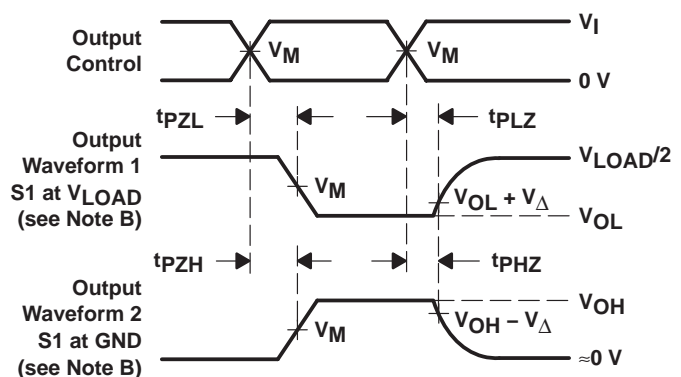
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .  
 D. The outputs are measured one at a time with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 5. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

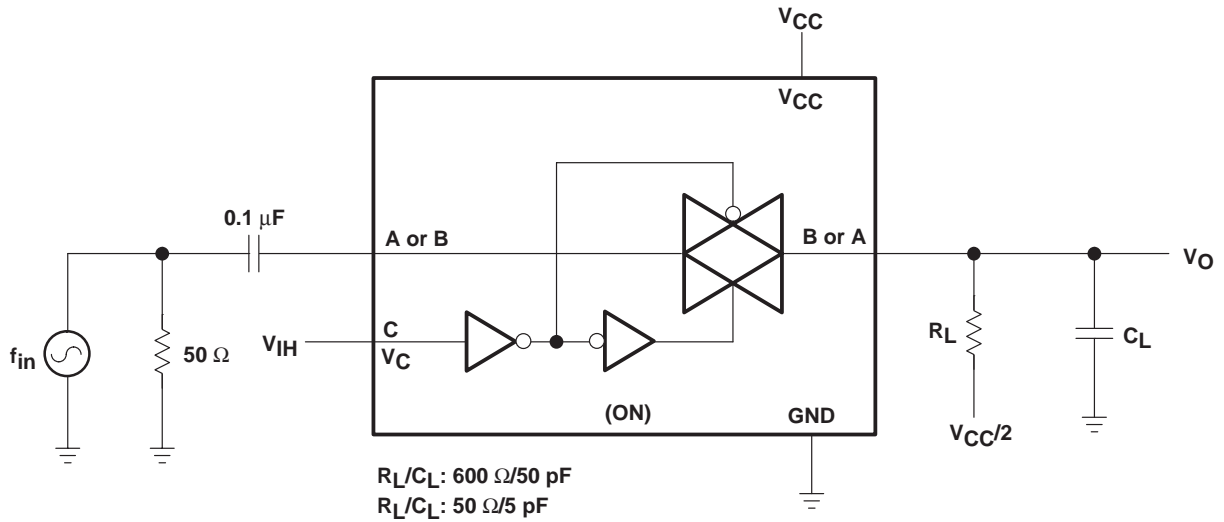


Figure 6. Frequency Response (Switch ON)

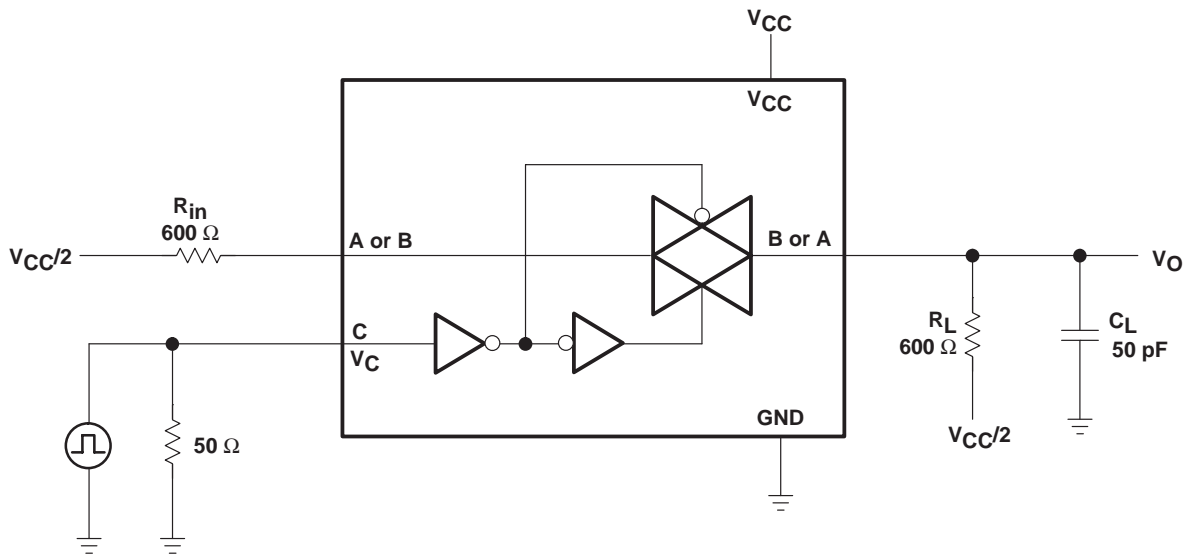


Figure 7. Crosstalk (Control Input – Switch Output)

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## PARAMETER MEASUREMENT INFORMATION

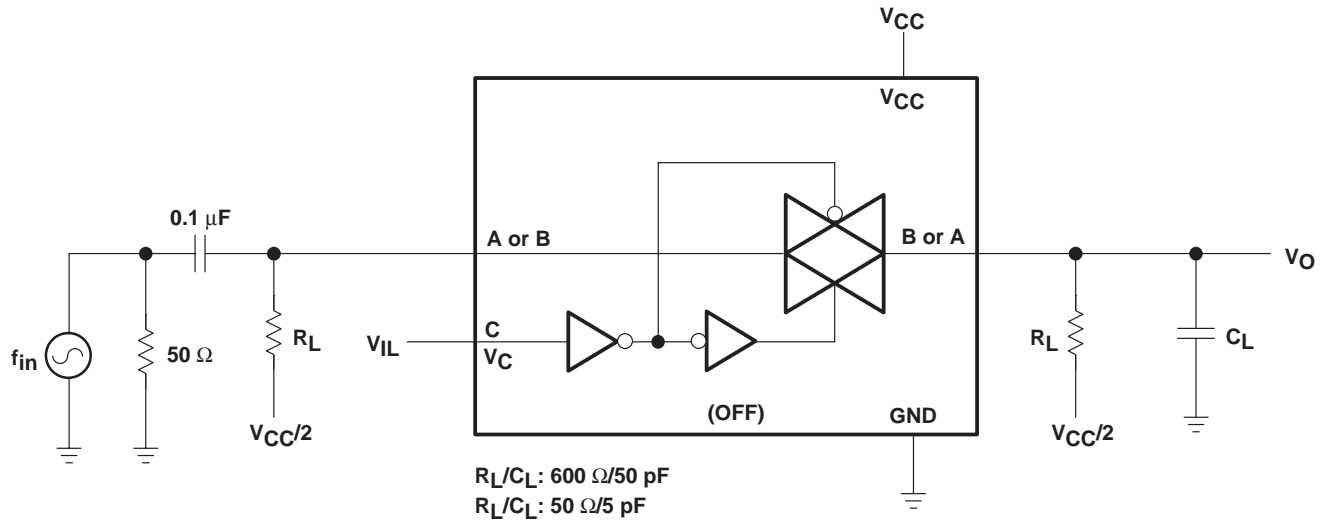


Figure 8. Feed-Through (Switch OFF)

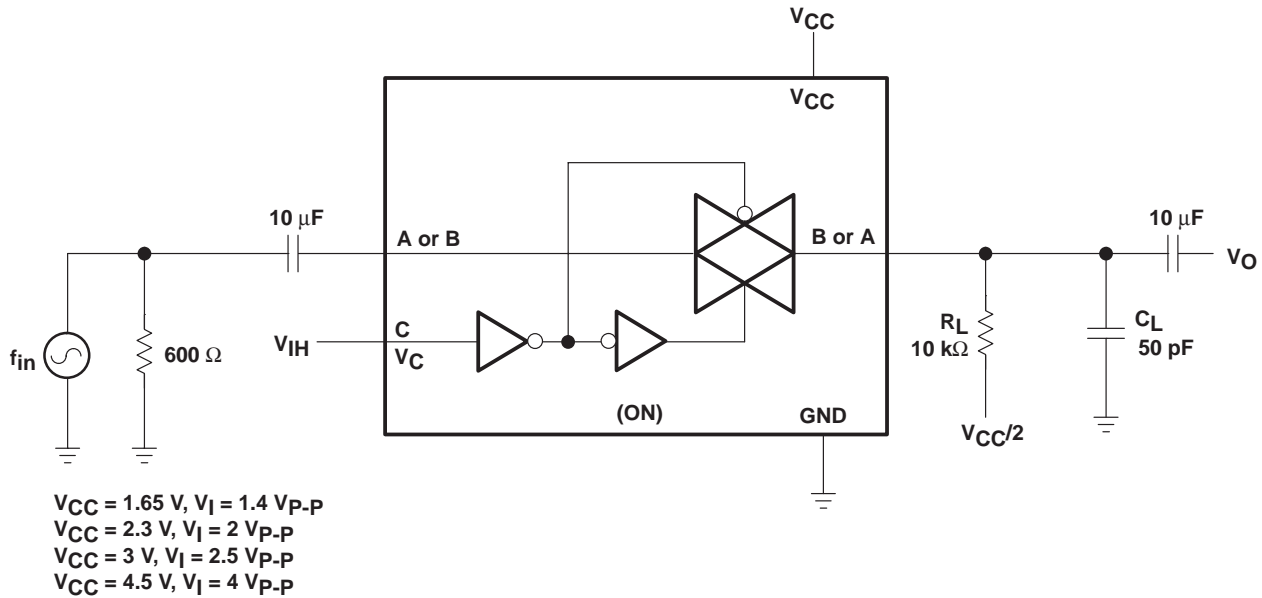


Figure 9. Sine-Wave Distortion

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVC1G66DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G66DBVT	ACTIVE	SOT-23	DBV	5	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G66DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G66DCKT	ACTIVE	SC70	DCK	5	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G66YEAR	ACTIVE	WCSP	YEA	5	3000	None	SNPB	Level-1-260C-UNLIM
SN74LVC1G66YEPR	ACTIVE	WCSP	YEP	5	3000	None	SNPB	Level-1-260C-UNLIM
SN74LVC1G66YZAR	ACTIVE	WCSP	YZA	5	3000	None	Call TI	Call TI
SN74LVC1G66YZPR	ACTIVE	WCSP	YZP	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

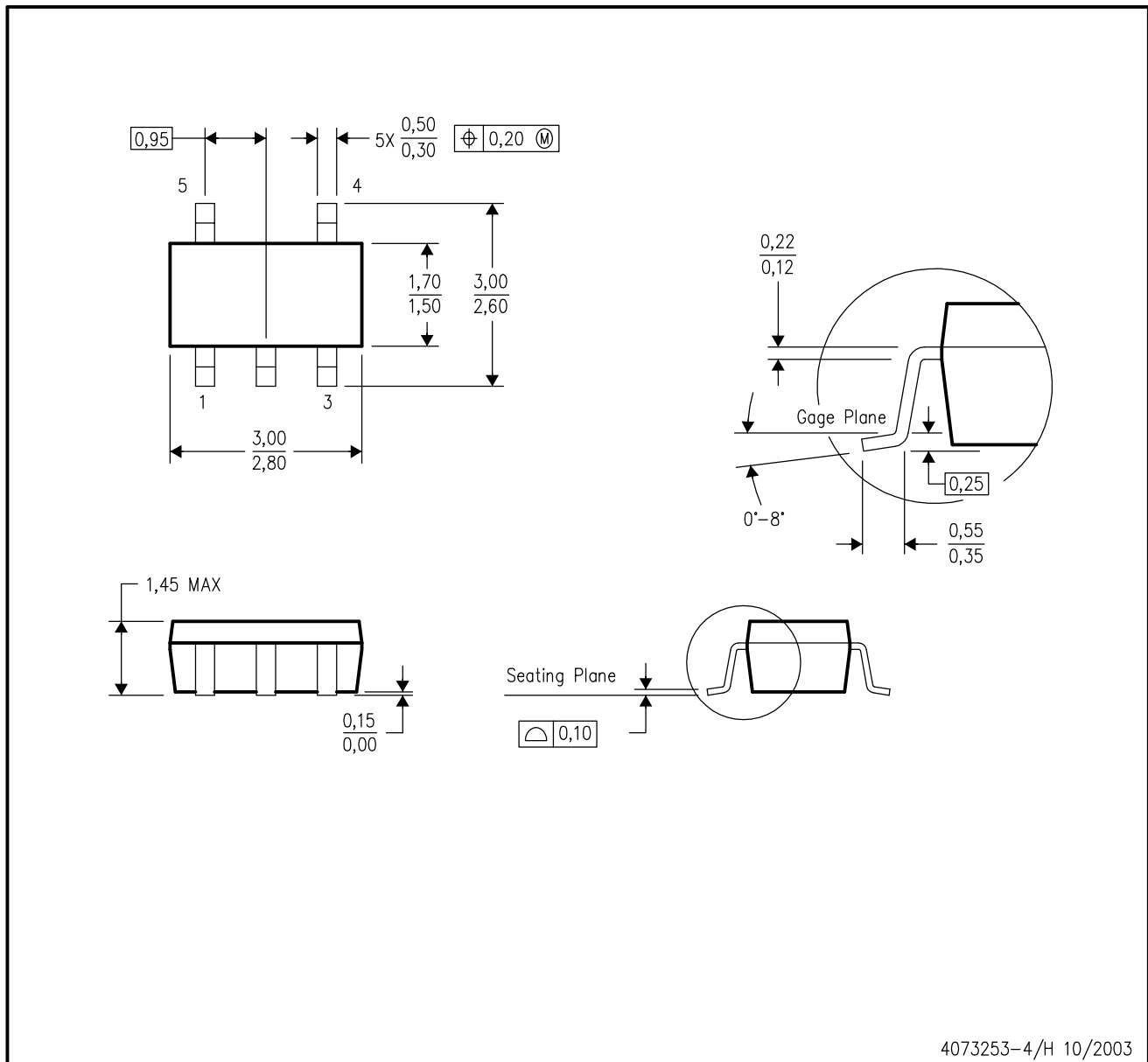
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G5)

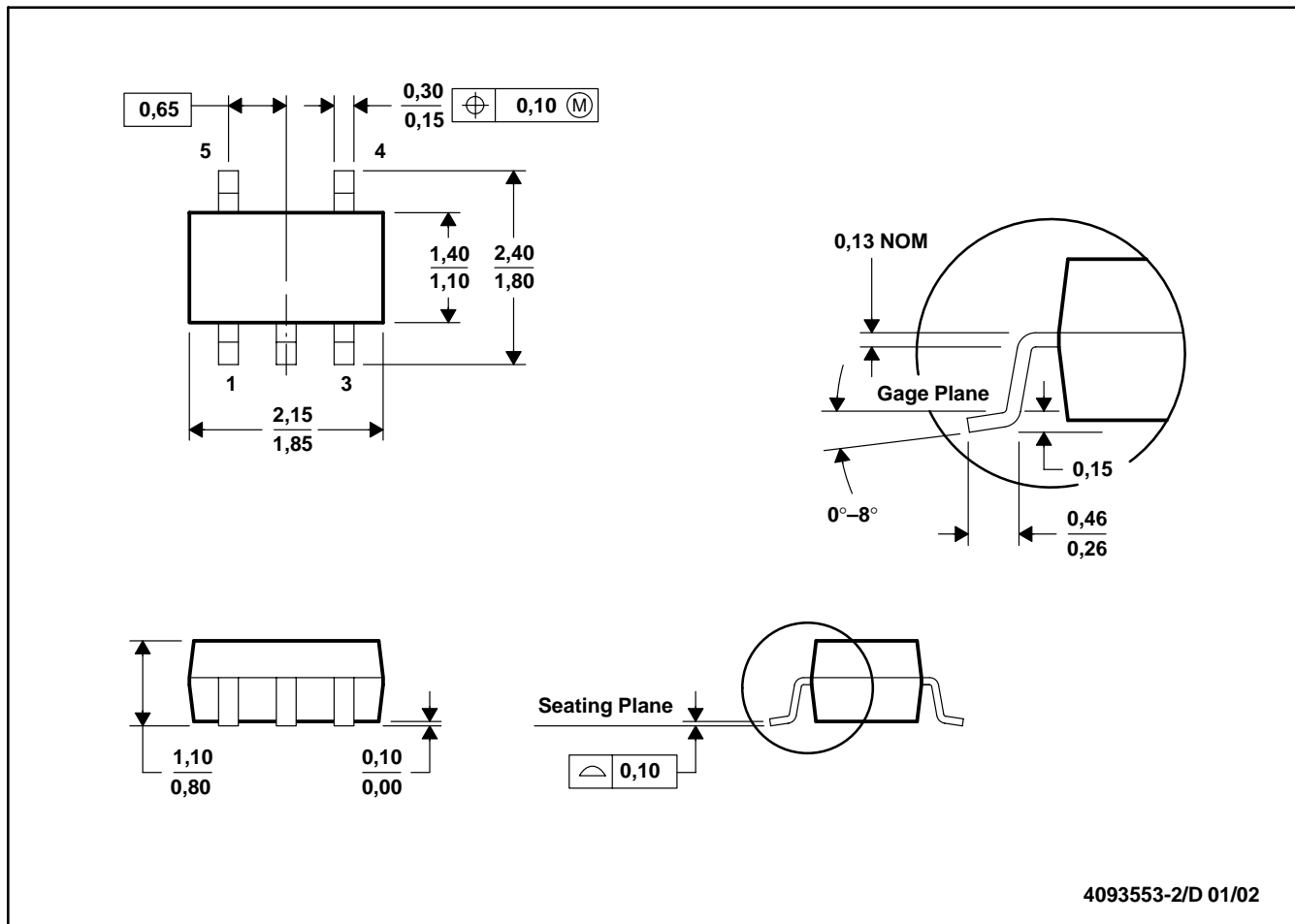
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion.
  - D. Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

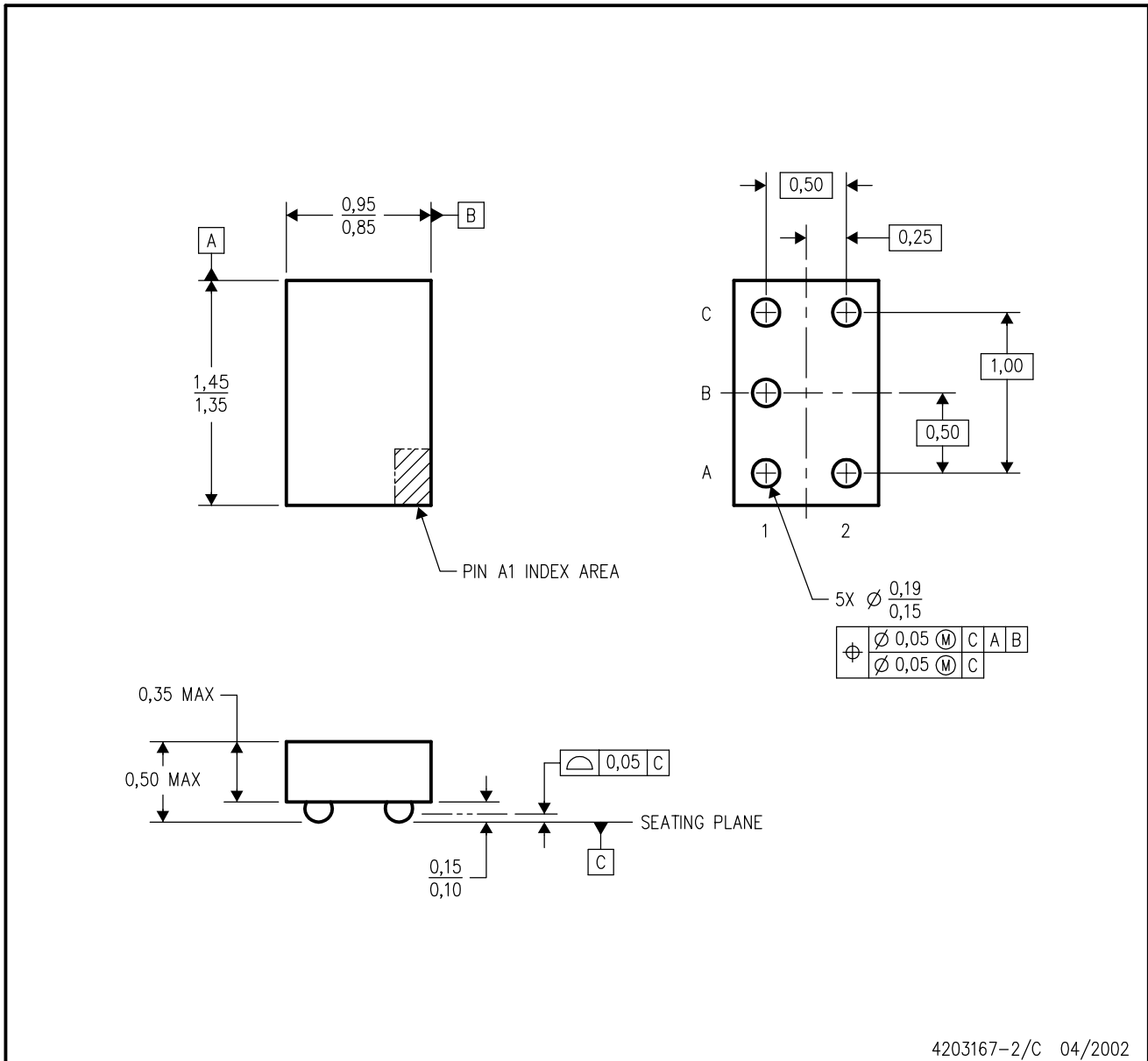
PLASTIC SMALL-OUTLINE PACKAGE



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 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.  
 D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

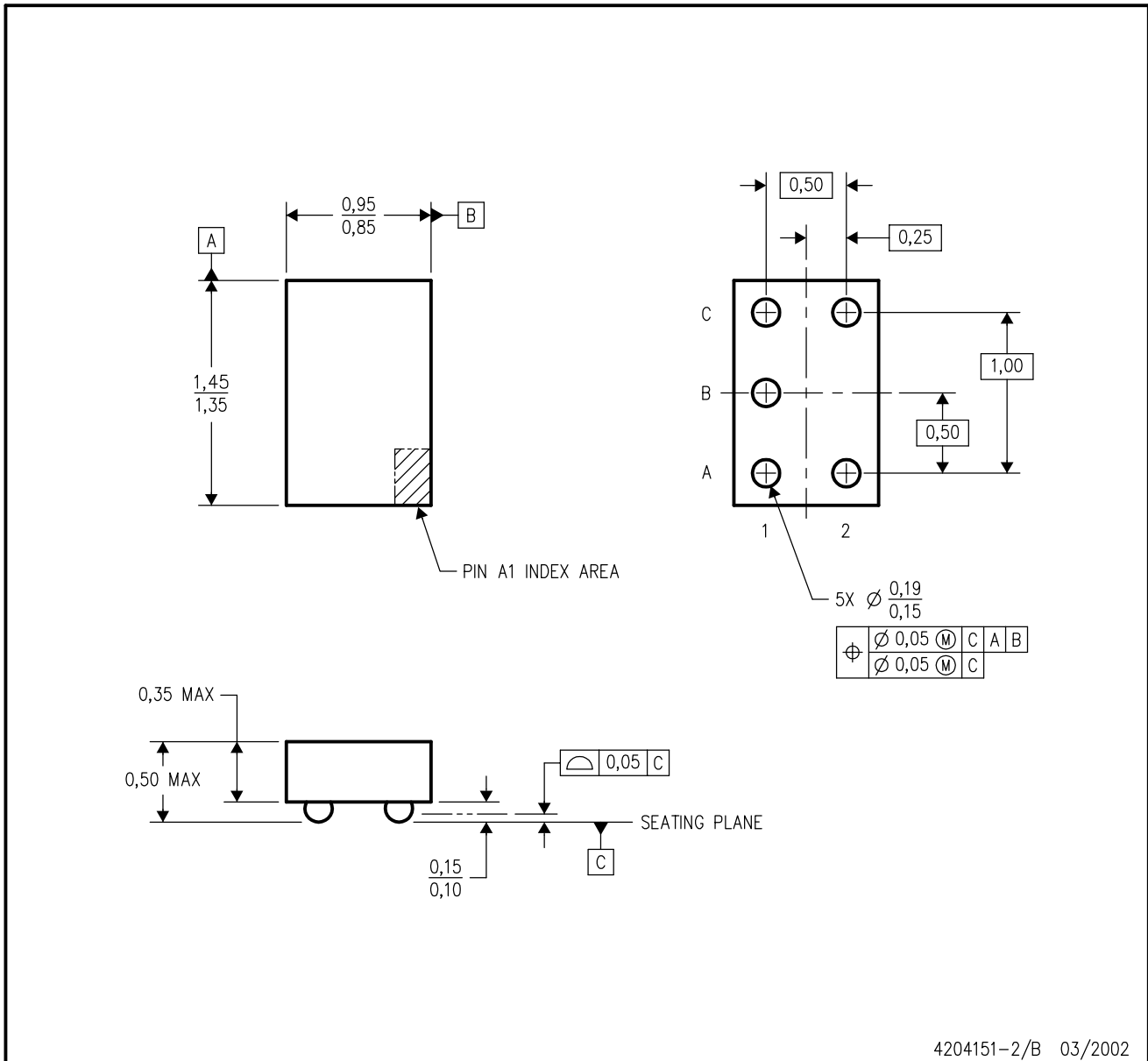


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

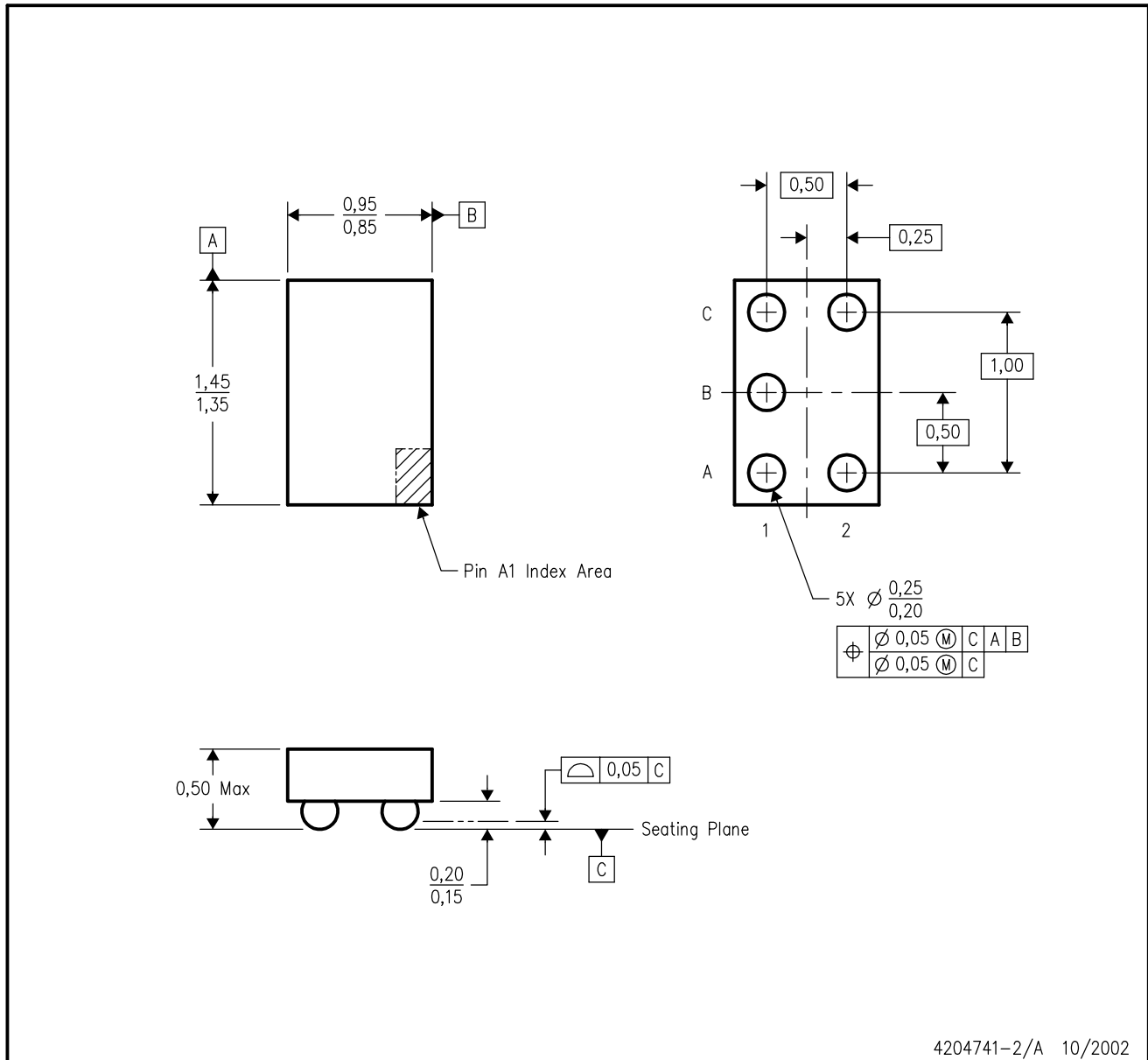


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

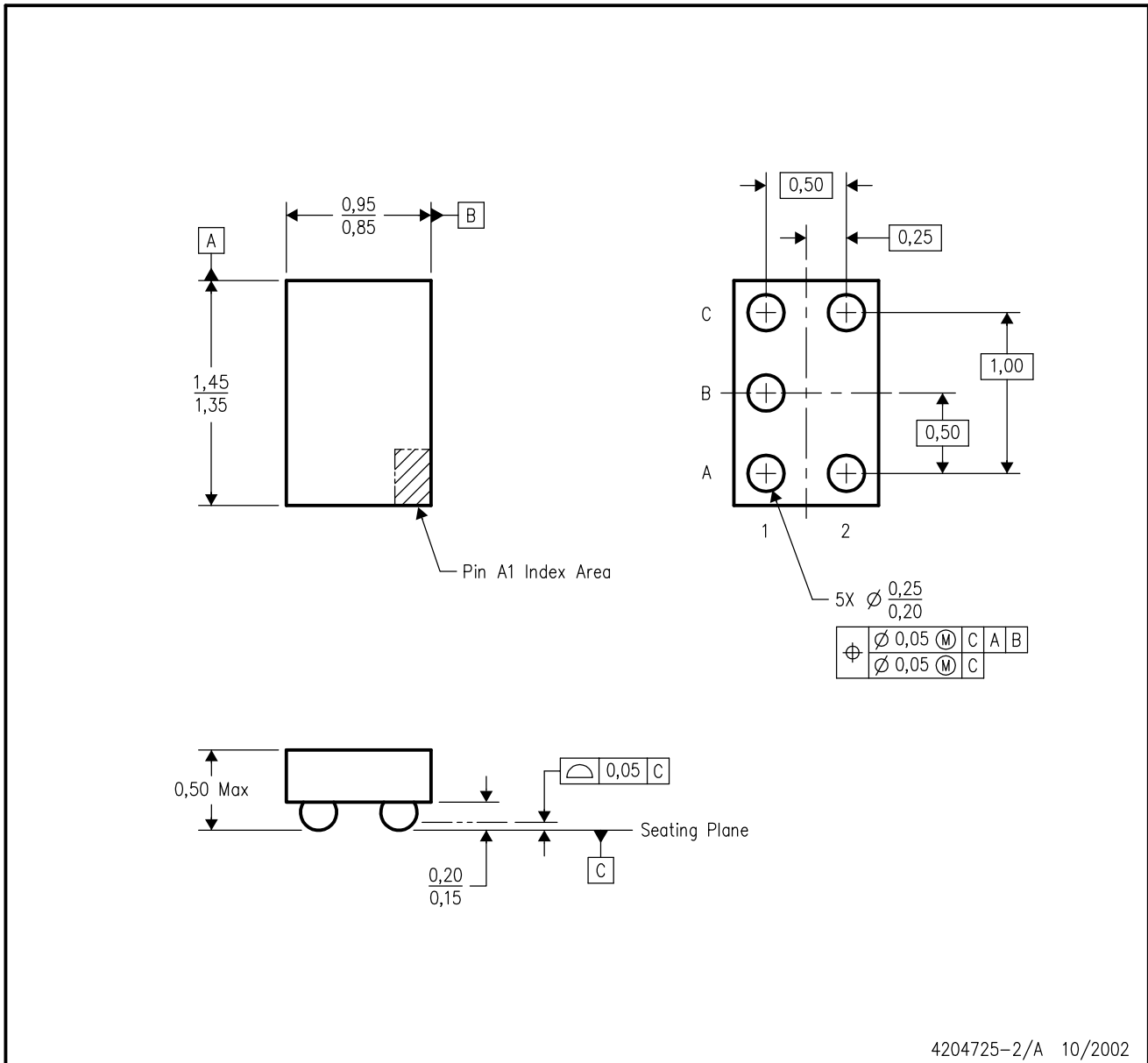


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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